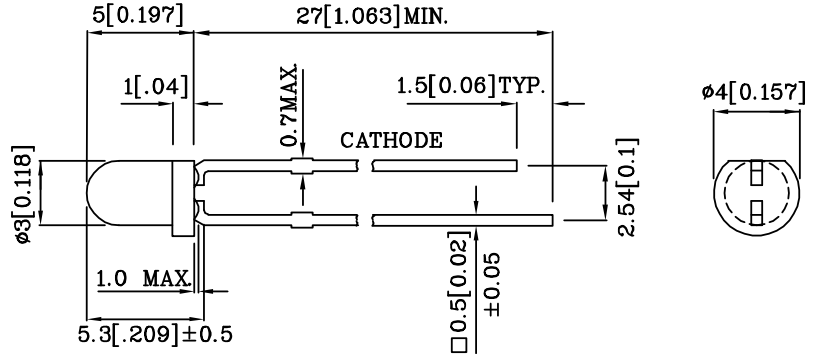


Features

- T-1 PACKAGE WITH RECTANGULAR BASE.
- WITH BUILT-IN BLINKING IC.
- OPERATION VOLTAGE FROM 3.5V TO 14V.
- BLINKING FREQUENCY FROM 3.0Hz TO 1.5Hz.
- RoHS COMPLIANT.



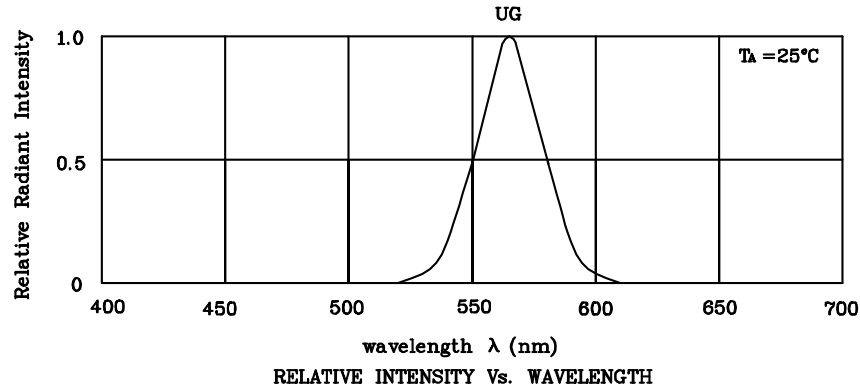
Notes:

1. All dimensions are in millimeters (inches).
2. Tolerance is $\pm 0.25(0.01)$ unless otherwise noted.

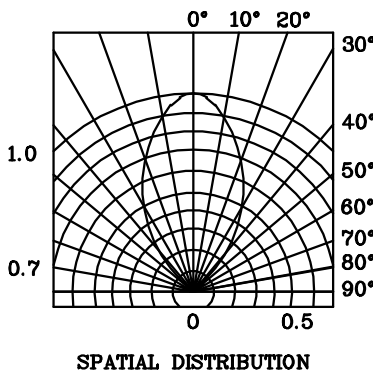
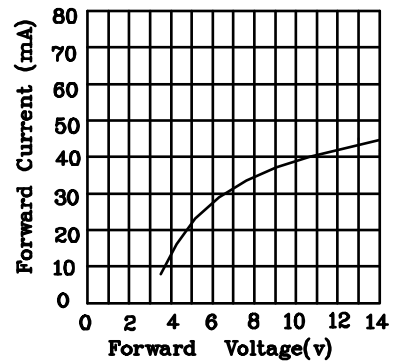
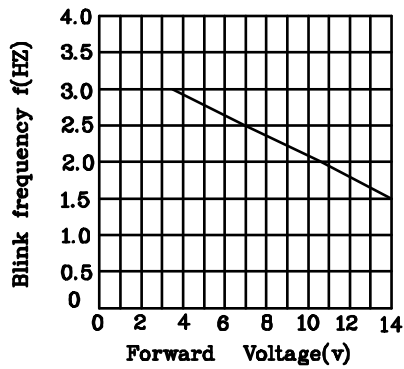
Absolute Maximum Ratings (TA=25°C)		UG (GaP)	Unit
Reverse Voltage	VR	0.5	V
Forward Voltage	VF	14	V
Power Dissipation	PT	310	mW
Operating Temperature	TA	-40 ~ +70	°C
Storage Temperature	Tstg	-40 ~ +85	
Lead Solder Temperature [2mm Below Package Base]	260°C For 3 Seconds		
Lead Solder Temperature [5mm Below Package Base]	260°C For 5 Seconds		

Operating Characteristics (TA=25°C)		UG (GaP)	Unit
Forward Current (Min.) (VF=3.5V)	IF	8	mA
Forward Current (Typ.) (VR=5V)	IF	22	mA
Supply Current (VF=3.5V)	ISON	8	mA
Supply Current (VF=14V)	ISON	44	mA
Blink Frequency (VF=3.5V)	f	3	Hz
Blink Frequency (VF=14V)	f	1.5	Hz
Wavelength of Peak Emission	λP	565	nm
Wavelength of Dominant Emission	λD	568	nm
Spectral Line Full Width At Half-Maximum	$\Delta\lambda$	30	nm

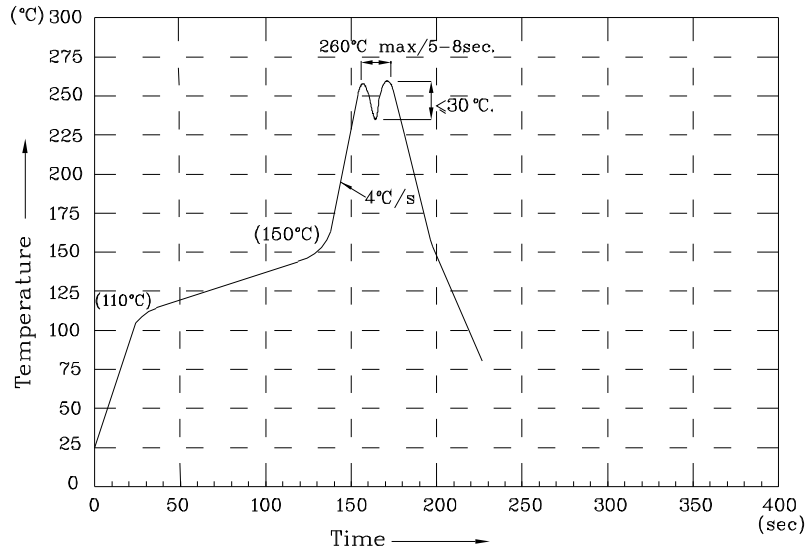
Part Number	Emitting Color	Emitting Material	Lens-color	Luminous Intensity (V= 9V) mcd		Wavelength nm λP	Viewing Angle 2 θ 1/2
				min.	typ.		
BUG34D	Green	GaP	Green Diffused	5	14	565	60°
Published Date : SEP 08,2005 Drawing No : SDSA3460 V2 Checked : B.L.LIU P.1/3							



❖ UG



Wave Soldering Profile For Lead-free Through-hole LED.



NOTES:

- 1.Recommend the wave temperature 245°C~260°C.The maximum soldering temperature should be less than 260°C.
- 2.Do not apply stress on epoxy resins when temperature is over 85 degree°C.
- 3.The soldering profile apply to the lead free soldering (Sn/Cu/Ag alloy).
- 4.No more than once.